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"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "<u>Embedded -</u> <u>Microcontrollers</u>"

Details

Detuils	
Product Status	Obsolete
Core Processor	PIC
Core Size	8-Bit
Speed	16MHz
Connectivity	I ² C, SPI, UART/USART
Peripherals	Brown-out Detect/Reset, POR, PWM, WDT
Number of I/O	50
Program Memory Size	32KB (16K x 16)
Program Memory Type	OTP
EEPROM Size	-
RAM Size	902 x 8
Voltage - Supply (Vcc/Vdd)	4.5V ~ 5.5V
Data Converters	A/D 12x10b
Oscillator Type	External
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	68-LCC (J-Lead)
Supplier Device Package	68-PLCC (24.23x24.23)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/pic17c756a-16e-l

Email: info@E-XFL.COM

Address: Room A, 16/F, Full Win Commercial Centre, 573 Nathan Road, Mongkok, Hong Kong

TABLE 3-1:	PINC	DUT DE	SCRIP	TIONS	(CON	TINUE	D)	
	F	PIC17C7	5X	PIC17	7C76X			
Name	DIP No.	PLCC No.	TQFP No.	PLCC No.	QFP No.	I/O/P Type	Buffer Type	Description
								PORTC is a bi-directional I/O Port.
RC0/AD0	2	3	58	3	72	I/O	TTL	This is also the least significant byte (LSB) of
RC1/AD1	63	67	55	83	69	I/O	TTL	the 16-bit wide system bus in Microprocessor
RC2/AD2	62	66	54	82	68	I/O	TTL	mode or Extended Microcontroller mode. In
RC3/AD3	61	65	53	81	67	I/O	TTL	multiplexed system bus configuration, these pins are address output as well as data input of
RC4/AD4	60	64	52	80	66	I/O	TTL	output.
RC5/AD5	58	63	51	79	65	I/O	TTL	
RC6/AD6	58	62	50	78	64	I/O	TTL	
RC7/AD7	57	61	49	77	63	I/O	TTL	
								PORTD is a bi-directional I/O Port.
RD0/AD8	10	11	2	15	4	I/O	TTL	This is also the most significant byte (MSB) of
RD1/AD9	9	10	1	14	3	I/O	TTL	the 16-bit system bus in Microprocessor mode
RD2/AD10	8	9	64	9	78	I/O	TTL	or Extended Microcontroller mode. In multi-
RD3/AD11	7	8	63	8	77	I/O	TTL	plexed system bus configuration, these pins an address output as well as data input or output.
RD4/AD12	6	7	62	7	76	I/O	TTL	
RD5/AD13	5	6	61	6	75	I/O	TTL	
RD6/AD14	4	5	60	5	74	I/O	TTL	
RD7/AD15	3	4	59	4	73	I/O	TTL	
								PORTE is a bi-directional I/O Port.
RE0/ALE	11	12	3	16	5	I/O	TTL	In Microprocessor mode or Extended Microcor troller mode, RE0 is the Address Latch Enable (ALE) output. Address should be latched on the falling edge of ALE output.
RE1/OE	12	13	4	17	6	I/O	TTL	In Microprocessor or Extended Microcontroller mode, RE1 is the Output Enable (OE) control output (active low).
RE2/WR	13	14	5	18	7	I/O	TTL	In Microprocessor or Extended Microcontroller mode, RE2 is the Write Enable (WR) control output (active low).
RE3/CAP4	14	15	6	19	8	I/O	ST	RE3 can also be the Capture4 input pin.
								PORTF is a bi-directional I/O Port.
RF0/AN4	26	28	18	36	24	I/O	ST	RF0 can also be analog input 4.
RF1/AN5	25	27	17	35	23	I/O	ST	RF1 can also be analog input 5.
RF2/AN6	24	26	16	30	18	I/O	ST	RF2 can also be analog input 6.
RF3/AN7	23	25	15	29	17	I/O	ST	RF3 can also be analog input 7.
RF4/AN8	22	24	14	28	16	I/O	ST	RF4 can also be analog input 8.
RF5/AN9	21	23	13	27	15	I/O	ST	RF5 can also be analog input 9.
RF6/AN10	20	22	12	26	14	I/O	ST	RF6 can also be analog input 10.
RF7/AN11	19	21	11	25	13	I/O	ST	RF7 can also be analog input 11.

TABLE 3-1: PINOUT DESCRIPTIONS (CONTINUED)

Legend: I = Input only; O = Output only; I/O = Inp P = Power; — = Not Used; TTL = T

I/O = Input/Output; TTL = TTL input;

ST = Schmitt Trigger input

Note 1: The output is only available by the peripheral operation.2: Open drain input/output pin. Pin forced to input upon any device RESET.

13.0 TIMER1, TIMER2, TIMER3, PWMS AND CAPTURES

The PIC17C7XX has a wealth of timers and time based functions to ease the implementation of control applications. These time base functions include three PWM outputs and four Capture inputs.

Timer1 and Timer2 are two 8-bit incrementing timers, each with an 8-bit period register (PR1 and PR2, respectively) and separate overflow interrupt flags. Timer1 and Timer2 can operate either as timers (increment on internal FOSC/4 clock), or as counters (increment on falling edge of external clock on pin RB4/TCLK12). They are also software configurable to operate as a single 16-bit timer/counter. These timers are also used as the time base for the PWM (Pulse Width Modulation) modules.

Timer3 is a 16-bit timer/counter which uses the TMR3H and TMR3L registers. Timer3 also has two additional registers (PR3H/CA1H:PR3L/CA1L) that are configurable as a 16-bit period register or a 16-bit capture register. TMR3 can be software configured to increment from the internal system clock (FOSC/4), or from an external signal on the RB5/TCLK3 pin. Timer3 is the time base for all of the 16-bit captures.

Six other registers comprise the Capture2, Capture3, and Capture4 registers (CA2H:CA2L, CA3H:CA3L, and CA4H:CA4L).

Figure 13-1, Figure 13-2 and Figure 13-3 are the control registers for the operation of Timer1, Timer2 and Timer3, as well as PWM1, PWM2, PWM3, Capture1, Capture2, Capture3 and Capture4.

Table 13-1 shows the Timer resource requirements for these time base functions. Each timer is an open resource so that multiple functions may operate with it.

TABLE 13-1: TIME-BASE FUNCTION/ RESOURCE REQUIREMENTS

Time Base Function	Timer Resource
PWM1	Timer1
PWM2	Timer1 or Timer2
PWM3	Timer1 or Timer2
Capture1	Timer3
Capture2	Timer3
Capture3	Timer3
Capture4	Timer3

REGISTER 13-1: TCON1 REGISTER (ADDRESS: 16h, BANK 3)

	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0	R/W-0			
	CA2ED1	CA2ED0	CA1ED1	CA1ED0	T16	TMR3CS	TMR2CS	TMR1CS			
	bit 7							bit 0			
bit 7-6	CA2ED1:CA2ED0: Capture2 Mode Select bits										
		ure on every ure on every									
		ure on every		dae							
	•	ure on every	•	•							
bit 5-4		CA1ED0: Ca	•								
		ure on every									
	•	ure on every ure on every	• •	dae							
		ure on every									
bit 3		r2:Timer1 Mo									
		2 and Timer1 2 and Timer1									
bit 2		Timer3 Cloc									
DILZ		increments of			RB5/TCLK	3 pin					
		increments of									
bit 1	TMR2CS:	Timer2 Cloc	k Source Se	lect bit							
		increments of			RB4/TCLK	l2 pin					
L	• • • • • • • • •	increments of									
bit 0		Timer1 Cloc			RB4/TCLK	l2 nin					
	1 = TMR1 increments off the falling edge of the RB4/TCLK12 pin 0 = TMR1 increments off the internal clock										
	Legend:										
	R = Reada	ble bit	W = W	/ritable bit	U = Unir	nplemented b	oit, read as '0)'			
	- n = Value	at POR Res	et '1' = B	it is set	'0' = Bit i	s cleared	x = Bit is u	nknown			

PIC17C7XX

NOTES:

REGISTER 15-1: SSPSTAT: SYNC SERIAL PORT STATUS REGISTER (ADDRESS: 13h, BANK 6) R/W-0 R/W-0 R-0 R-0 R-0 R-0 R-0 R-0 SMP CKE D/A Р S R/W UA BF bit 7 bit 0 bit 7 SMP: Sample bit SPI Master mode: 1 = Input data sampled at end of data output time 0 = Input data sampled at middle of data output time SPI Slave mode: SMP must be cleared when SPI is used in Slave mode In I²C Master or Slave mode: 1 = Slew rate control disabled for Standard Speed mode (100 kHz and 1 MHz) 0 = Slew rate control enabled for High Speed mode (400 kHz) bit 6 CKE: SPI Clock Edge Select (Figure 15-6, Figure 15-8 and Figure 15-9) CKP = 0: 1 = Data transmitted on rising edge of SCK 0 = Data transmitted on falling edge of SCK CKP = 1: 1 = Data transmitted on falling edge of SCK 0 = Data transmitted on rising edge of SCK bit 5 D/A: Data/Address bit (I²C mode only) 1 = Indicates that the last byte received or transmitted was data 0 = Indicates that the last byte received or transmitted was address P: STOP bit bit 4 $(l^2C \text{ mode only})$. This bit is cleared when the MSSP module is disabled, SSPEN is cleared.) 1 = Indicates that a STOP bit has been detected last (this bit is '0' on RESET) 0 = STOP bit was not detected last bit 3 S: START bit (I²C mode only. This bit is cleared when the MSSP module is disabled, SSPEN is cleared.) 1 = Indicates that a START bit has been detected last (this bit is '0' on RESET) 0 = START bit was not detected last **R/W**: Read/Write bit Information (I²C mode only) bit 2 This bit holds the R/W bit information following the last address match. This bit is only valid from the address match to the next START bit, STOP bit, or not ACK bit. In I²C Slave mode: 1 = Read0 = WriteIn I²C Master mode: 1 = Transmit is in progress 0 = Transmit is not in progress Oring this bit with SEN, RSEN, PEN, RCEN, or ACKEN will indicate if the MSSP is in IDLE mode. bit 1 **UA**: Update Address (10-bit I²C mode only) 1 = Indicates that the user needs to update the address in the SSPADD register 0 = Address does not need to be updated bit 0 BF: Buffer Full Status bit Receive (SPI and I²C modes) 1 = Receive complete, SSPBUF is full 0 = Receive not complete, SSPBUF is empty Transmit (I²C mode only) 1 = Data transmit in progress (does not include the ACK and STOP bits), SSPBUF is full 0 = Data transmit complete (does not include the ACK and STOP bits), SSPBUF is emptyLegend: R = Readable bit W = Writable bit U = Unimplemented bit, read as '0'

15.2.3 SLEEP OPERATION

While in SLEEP mode, the I^2C module can receive addresses or data and when an address match or complete byte transfer occurs, wake the processor from SLEEP (if the SSP interrupt is enabled).

15.2.4 EFFECTS OF A RESET

A RESET disables the SSP module and terminates the current transfer.

Address	Name	Bit 7	Bit 6	Bit 5	Bit 4	Bit 3	Bit 2	Bit 1	Bit 0	POR, BOR	MCLR, WDT
07h, Unbanked	INTSTA	PEIF	T0CKIF	TOIF	INTF	PEIE	T0CKIE	T0IE	INTE	0000 0000	0000 0000
10h, Bank 4	PIR2	SSPIF	BCLIF	ADIF	_	CA4IF	CA3IF	TX2IF	RC2IF	000- 0000	000- 0000
11h, Bank 4	PIE2	SSPIE	BCLIE	ADIE	_	CA4IE	CA3IE	TX2IE	RC2IE	000- 0000	000- 0000
10h. Bank 6	SSPADD	Synchror	nous Serial P	ort (I ² C mo	de) Addres	s Register				0000 0000	0000 0000
14h, Bank 6	SSPBUF	Synchror	nous Serial P	ort Receive	Buffer/Tra	nsmit Regi	ister			XXXX XXXX	սսսս սսսս
11h, Bank 6	SSPCON1	WCOL	SSPOV	SSPEN	CKP	SSPM3	SSPM2	SSPM1	SSPM0	0000 0000	0000 0000
12h, Bank 6	SSPCON2	GCEN	ACKSTAT	ACKDT	ACKEN	RCEN	PEN	RSEN	SEN	0000 0000	0000 0000
13h, Bank 6	SSPSTAT	SMP	CKE	D/A	Р	S	R/W	UA	BF	0000 0000	0000 0000

TABLE 15-3: REGISTERS ASSOCIATED WITH I²C OPERATION

Legend: x = unknown, u = unchanged, - = unimplemented, read as '0'. Shaded cells are not used by the SSP in I²C mode.



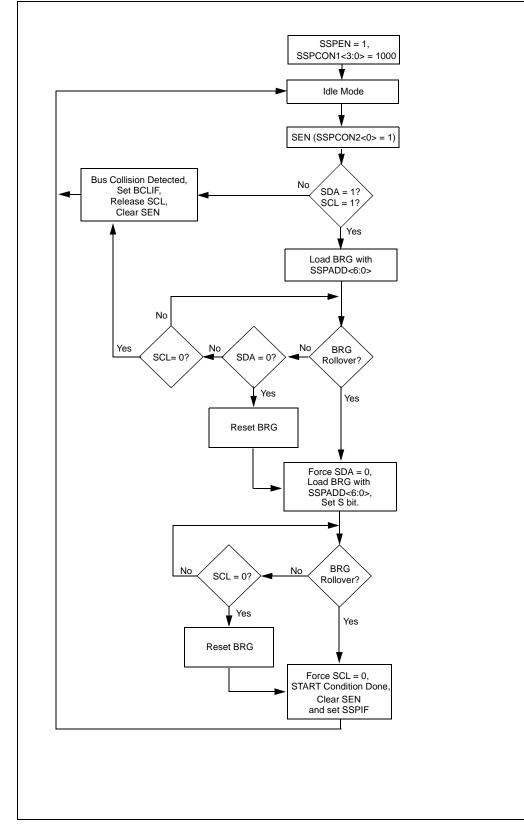
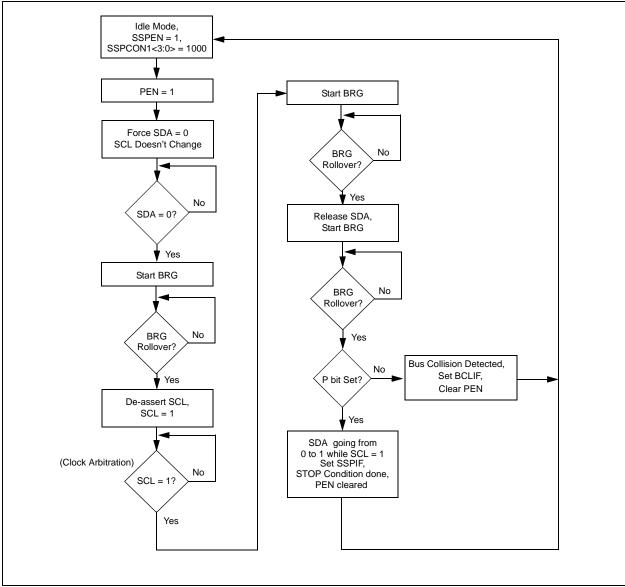


FIGURE 15-32: STOP CONDITION FLOW CHART



15.3 Connection Considerations for I²C Bus

For standard mode I^2C bus devices, the values of resistors $R_p R_s$ in Figure 15-42 depends on the following parameters:

- Supply voltage
- Bus capacitance
- Number of connected devices (input current + leakage current)

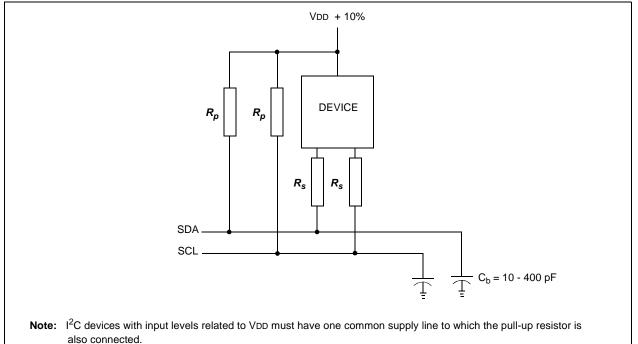
The supply voltage limits the minimum value of resistor R_p due to the specified minimum sink current of 3 mA at VoL max = 0.4V for the specified output stages. For

example, with a supply voltage of VDD = $5V \pm 10\%$ and VOL max = 0.4V at 3 mA, $R_p \min$ = (5.5-0.4)/0.003 = 1.7 k Ω . VDD as a function of R_p is shown in Figure 15-42. The desired noise margin of 0.1 VDD for the low level, limits the maximum value of R_s . Series resistors are optional and used to improve ESD susceptibility.

The bus capacitance is the total capacitance of wire, connections and pins. This capacitance limits the maximum value of R_p due to the specified rise time (Figure 15-42).

The SMP bit is the slew rate control enabled bit. This bit is in the SSPSTAT register and controls the slew rate of the I/O pins when in I^2C mode (master or slave).

FIGURE 15-42: SAMPLE DEVICE CONFIGURATION FOR I²C BUS



17.6 In-Circuit Serial Programming

The PIC17C7XX group of the high-end family (PIC17CXXX) has an added feature that allows serial programming while in the end application circuit. This is simply done with two lines for clock and data and three other lines for power, ground, and the programming voltage. This allows customers to manufacture boards with unprogrammed devices and then program the microcontroller just before shipping the product. This also allows the most recent firmware, or a custom firmware to be programmed.

Devices may be serialized to make the product unique; "special" variants of the product may be offered and code updates are possible. This allows for increased design flexibility.

To place the device into the Serial Programming Test mode, two pins will need to be placed at VIHH. These are the TEST pin and the MCLR/VPP pin. Also, a sequence of events must occur as follows:

- 1. The TEST pin is placed at VIHH.
- 2. The MCLR/VPP pin is placed at VIHH.

There is a setup time between step 1 and step 2 that must be met.

After this sequence, the Program Counter is pointing to program memory address 0xFF60. This location is in the Boot ROM. The code initializes the USART/SCI so that it can receive commands. For this, the device must be clocked. The device clock source in this mode is the RA1/T0CKI pin. After delaying to allow the USART/SCI to initialize, commands can be received. The flow is shown in these 3 steps:

- 1. The device clock source starts.
- 2. Wait 80 device clocks for Boot ROM code to configure the USART/SCI.
- 3. Commands may now be sent.

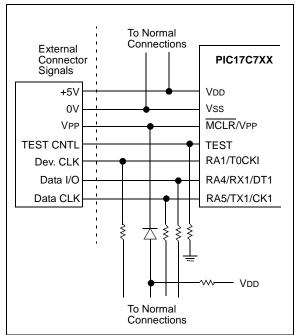
	During Programming					
Name	Function	Туре	Description			
RA4/RX1/DT1	DT	I/O	Serial Data			
RA5/TX1/CK1	СК	I	Serial Clock			
RA1/T0CKI	OSCI	I	Device Clock Source			
TEST	TEST	I	Test mode selection control input, force to VIHH			
MCLR/VPP	MCLR/VPP	Р	Master Clear Reset and Device Programming Voltage			
Vdd	Vdd	Р	Positive supply for logic and I/O pins			
Vss	Vss	Р	Ground reference for logic and I/O pins			

TABLE 17-3: ICSP INTERFACE PINS

For complete details of serial programming, please refer to the PIC17C7XX Programming Specification. (Contact your local Microchip Technology Sales Office for availability.)

FIGURE 17-3:

TYPICAL IN-CIRCUIT SERIAL PROGRAMMING CONNECTION



PIC17C7XX

MO\	/PF	Move p te	o f						
Synt	ax:	[label] N	[label] MOVPF p,f						
Ope	rands:		$\begin{array}{l} 0 \leq f \leq 255 \\ 0 \leq p \leq 31 \end{array}$						
Ope	ration:	$(p) \to (f)$							
Statu	us Affected:	Z							
Enco	oding:	010p	рррр	ffff	ffff				
Des	cription:	'p' to data r 'f' can be a space (00h to 1Fh. Either 'p' o special situ MOVPFis p ring a perip	p' or 'f' can be WREG (a useful,						
		tion. Both '	or an I/O port) to a data memory loca- tion. Both 'f' and 'p' can be indirectly addressed.						
Wor	ds:	1							
Cycl	es:	1							
QC	ycle Activity:								
	Q1	Q2	Q3	3	Q4				
	Decode	Read register 'p'	Proce Dat		Write register 'f'				

Example:	MOVPF	REG1, REG2

Before	Instruction
Delote	manucuon

=	0x11					
=	0x33					
=	0x11					
	0x11					
	=					

MOVWF	Move WR	EG to f		
Syntax:	[label]	MOVWF	= f	
Operands:	$0 \le f \le 25$	5		
Operation:	(WREG) -	→ (f)		
Status Affected:	None			
Encoding:	0000	0001	ffff	ffff
Description:		can be a		register 'f'. ere in the 256
Words:	1			
Cycles:	1			
Q Cycle Activity:				
Q1	Q2	Q3		Q4
Decode	Read register 'f'	Proce Data		Write register 'f'
Example:	MOVWF	REG		
Before Instru WREG REG	iction = 0x4F = 0xFF			

=

0x4F

0x4F

After Instruction WREG =

REG

RET	FIE	Return fro	Return from Interrupt				LW	Returi
Synt	ax:	[label] I	RETFIE		-	Synt	[label	
Ope	rands:	None				Ope	rands:	0 ≤ k ≤
Ope	ration:	$\begin{array}{l} TOS \rightarrow (P \\ 0 \rightarrow GLIN \end{array}$	TD;			Operation:		
PCLATH is unchanged.					State	us Affected:	None	
State	us Affected:	GLINTD			_	Enco	oding:	1011
Enco	oding:	0000	0000 000	0 0101		Des	cription:	WREG
Description: Return from Interrupt. Stack is POP'ed and Top-of-Stack (TOS) is loaded in the PC. Interrupts are enabled by clearing the GLINTD bit. GLINTD is the global			_			'k'. The the top The hig remain		
		interrupt dis	able bit (CPU	STA<4>).		Wor	ds:	1
Wor	ds:	1				Cycl	es:	2
Cycl	es:	2				QC	ycle Activity:	
QC	ycle Activity:						Q1	Q2
	Q1	Q2	Q3	Q4			Decode	Read
	Decode	No operation	Clear GLINTD	POP PC from stack				literal '
	No	No	No	No			No	No
	operation	operation	operation	operation]		operation	operatio
<u>Exa</u>	<u>mple</u> :	RETFIE				F		CALLT
	After Interrupt PC = TOS GLINTD = 0					<u>Exai</u>	<u>mple</u> :	CALL T

RET	LW	Return Li	Return Literal to WREG					
Synt	ax:	[label]	[label] RETLW k					
Ope	rands:	$0 \le k \le 25$	$0 \le k \le 255$					
Ope	ration:	· ·	$k \rightarrow (WREG); TOS \rightarrow (PC);$ PCLATH is unchanged					
State	us Affected:	None						
Enco	oding:	1011	0110	kkkk	kkkk			
Description:		'k'. The pro the top of th The high a	WREG is loaded with the eight-bit literal 'k'. The program counter is loaded from the top of the stack (the return address). The high address latch (PCLATH) remains unchanged.					
Wor	ds:	1	1					
Cycl	es:	2	2					
QC	vcle Activity:							
	Q1	Q2	Q3	3	Q4			
	Decode	Read literal 'k'	Proce Dat		POP PC rom stack, Write to WREG			
	No	No	No		No			
	operation	operation	opera	tion	operation			
<u>Example</u> :		; WR	et value EG now has e value ; ; WREG :	s = offset	ble			

. RETLW kn ; End of table

0x07

WREG = value of k7

Before Instruction WREG =

After Instruction

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TABLRD	Table Read		<u> </u>
Example1:	TABLRD 1, 1, R	EG ;	S
Before Instruc REG TBLATH TBLATL TBLPTR MEMORY	ction = = = = (TBLPTR) =	0x53 0xAA 0x55 0xA356 0x1234	0
REG TBLATH TBLATL TBLPTR MEMORY	on (table write co = = (TBLPTR) =	0xAA 0x12 0x34 0xA357 0x5678	
Example2:	TABLRD 0, 0, R	EG;	S
Before Instruc REG TBLATH TBLATL TBLPTR MEMORY	ction = = = = (TBLPTR) =	0x53 0xAA 0x55 0xA356 0x1234	E
REG TBLATH TBLATL TBLPTR	on (table write co = = = (TBLPTR) =	0x55 0x12 0x34 0xA356 0x1234	
			M C

TAB	LWT	Table Write					
Synt	ax:	[label] TABLWT t,i,f					
Ope	rands:	$0 \le f \le 255$ i $\in [0,1]$ t $\in [0,1]$					
Ope	ration:	If t = 0, f \rightarrow TBLATL; If t = 1, f \rightarrow TBLATH; TBLAT \rightarrow Prog Mem (TBLPTR); If i = 1, TBLPTR + 1 \rightarrow TBLPTR If i = 0, TBLPTR is unchanged					
Statu	us Affected	None					
Enco	oding:	1010 11ti ffff ffff					
voltage m <u>emory</u> If MCLR the prog		CLR/VPP = VDD programming sequence of internal memory be interrupted. A short write will occur (2 . The internal memory location will not be					
	affec	3. The TBLPTR can be automati-					
		cally incremented					
		If i = 1; TBLPTR is not incremented					
		If i = 0; TBLPTR is incremented					
Wor	ds:	1					
Cycl	es:	2 (many if write is to on-chip EPROM program memory)					
QC	Q Cycle Activity:						
	Q1	Q2 Q3 Q4					
	Decode	Read Process Write register 'f' Data register TBLATH or TBLATL					
	No operation	NoNoNooperationoperationoperation(Table Pointer(Table Latch onon AddressAddress bus,bus)WR goes low)					

PIC17C7XX

NOTES:

PIC17LC7XX-08			Standard Operating Conditions (unless otherwise stated) Operating temperature				
(Commercial, Industrial)			-40°C \leq TA \leq +85°C for industrial and 0°C \leq TA \leq +70°C for commercial				
			Standard Operating		ng Cond ature -4 -4	itions (u 0°C ≤ TA 0°C ≤ T⁄	nless otherwise stated) $\leq +125^{\circ}$ C for extended $A \leq +85^{\circ}$ C for industrial $A \leq +70^{\circ}$ C for commercial
Param. No.	Sym	Characteristic	Min	Тур†	Мах	Units	Conditions
D010	Idd	Supply Current (Note 2	2)				
		PIC17LC7XX	—	3	6	mA	Fosc = 4 MHz (Note 4)
D010		PIC17C7XX	—	3	6	mA	Fosc = 4 MHz (Note 4)
D011		PIC17LC7XX	—	5	10	mA	Fosc = 8 MHz
D011 D012		PIC17C7XX	_	5 9	10 18	mA mA	Fosc = 8 MHz Fosc = 16 MHz
D014		PIC17LC7XX	—	85	150	μΑ	Fosc = 32 kHz, (EC osc configuration)
D015		PIC17C7XX	—	15	30	mA	Fosc = 33 MHz
D021	IPD	Power-down Current (Note 3)				
		PIC17LC7XX	—	<1	5	μA	VDD = 3.0V, WDT disabled
D021 (commercial, industrial) D021A (extended)		PIC17C7XX	_	<1 2	20 20	μΑ	VDD = 5.5V, WDT disabled VDD = 5.5V, WDT disabled
		Module Differential Current					
D023	∆lbor	BOR circuitry	_	75	150	μA	VDD = 4.5V, BODEN enabled
D024	∆IWDT	Watchdog Timer	-	10	35	μΑ	VDD = 5.5V
D026	ΔIAD	A/D converter	_	1	-	μA	VDD = 5.5V, A/D not converting

† Data in "Typ" column is at 5V, 25°C unless otherwise stated.

Note 1: This is the limit to which VDD can be lowered in SLEEP mode without losing RAM data.

2: The supply current is mainly a function of the operating voltage and frequency. Other factors such as I/O pin loading and switching rate, oscillator type, internal code execution pattern and temperature also have an impact on the current consumption.

The test conditions for all IDD measurements in active operation mode are:

<u>OSC1</u> = external square wave, from rail to rail; all I/O pins tri-stated, pulled to VDD or VSS, T0CKI = VDD, MCLR = VDD; WDT disabled.

Current consumed from the oscillator and I/O's driving external capacitive or resistive loads needs to be considered.

For the RC oscillator, the current through the external pull-up resistor (R) can be estimated as: $VDD/(2 \bullet R)$.

For capacitive loads, the current can be estimated (for an individual I/O pin) as (CL \bullet VDD) \bullet f

CL = Total capacitive load on the I/O pin; f = average frequency the I/O pin switches.

The capacitive currents are most significant when the device is configured for external execution (includes Extended Microcontroller mode).

- **3:** The power-down current in SLEEP mode does not depend on the oscillator type. Power-down current is measured with the part in SLEEP mode, with all I/O pins in hi-impedance state and tied to VDD or VSs.
- 4: For RC osc configuration, current through REXT is not included. The current through the resistor can be estimated by the formula IR = VDD/2REXT (mA) with REXT in kOhm.
- **5:** This is the voltage where the device enters the Brown-out Reset. When BOR is enabled, the device (-16) will operate correctly to this trip point.

20.3 Timing Parameter Symbology

The timing parameter symbols have been created following one of the following formats:

1. TppS2ppS		3. Tcc:st	(I ² C specifications only)
2. TppS		4. Ts	(I ² C specifications only)
Т			
F	Frequency	Т	Time
Lowerc	ase symbols (pp) and their meanings:		
рр			
ad	Address/Data	ost	Oscillator Start-Up Timer
al	ALE	pwrt	Power-Up Timer
сс	Capture1 and Capture2	rb	PORTB
ck	CLKOUT or clock	rd	RD
dt	Data in	rw	RD or WR
in	INT pin	tO	ТОСКІ
io	I/O port	t123	TCLK12 and TCLK3
mc	MCLR	wdt	Watchdog Timer
oe	OE	wr	WR
OS	OSC1		
Upperc	ase symbols and their meanings:		
S			
D	Driven	L	Low
E	Edge	Р	Period
F	Fall	R	Rise
Н	High	V	Valid
I	Invalid (Hi-impedance)	Z	Hi-impedance



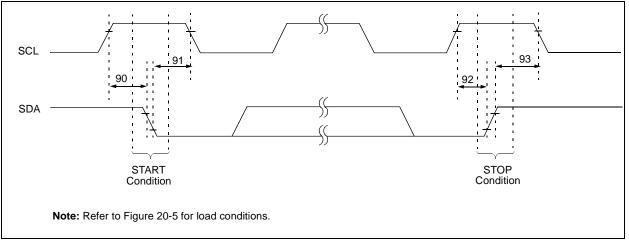


TABLE 20-12: I ² C	BUS START/STOP	BITS REQUIREMENTS
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Param. No.	Sym	Charac	teristic	Min	Ту р	Max	Units	Conditions
90	Tsu:sta	START condition	100 kHz mode	2(Tosc)(BRG + 1)	_	_	ns	Only relevant for
		Setup time	400 kHz mode	2(Tosc)(BRG + 1)	_	—		Repeated Start condition
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)	_	—		
91	Thd:sta	START condition	100 kHz mode	2(Tosc)(BRG + 1)	_	—	ns	After this period, the first
		Hold time	400 kHz mode	2(Tosc)(BRG + 1)		—		clock pulse is generated
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)		—		
92	Tsu:sto	STOP condition	100 kHz mode	2(Tosc)(BRG + 1)	_	—	ns	
		Setup time	400 kHz mode	2(Tosc)(BRG + 1)		—		
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)		—		
93	Thd:sto	STOP condition	100 kHz mode	2(Tosc)(BRG + 1)	_	—	ns	
		Hold time	400 kHz mode	2(Tosc)(BRG + 1)	_	—		
			1 MHz mode ⁽¹⁾	2(Tosc)(BRG + 1)	_	—		

Note 1: Maximum pin capacitance = 10 pF for all I²C pins.

21.0 PIC17C7XX DC AND AC CHARACTERISTICS

The graphs and tables provided in this section are for design guidance and are not tested nor guaranteed. In some graphs or tables the data presented is outside specified operating range (e.g., outside specified VDD range). This is for information only and devices are ensured to operate properly only within the specified range.

The data presented in this section is a statistical summary of data collected on units from different lots over a period of time.

- Typ or Typical represents the mean of the distribution at 25°C.
- Max or Maximum represents (mean + 3 σ) over the temperature range of -40°C to 85°C.
- Min or Minimum represents (mean 3σ) over the temperature range of -40°C to 85° C.
- **Note:** Standard deviation is denoted by sigma (σ).

TABLE 21-1: PIN CAPACITANCE PER PACKAGE TYPE

Pin Name	Typical Capacitance (pF)				
	68-pin PLCC	64-pin TQFP			
All pins, except MCLR, VDD, and Vss	10	10			
MCLR pin	20	20			

FIGURE 21-1: TYPICAL RC OSCILLATOR FREQUENCY vs. TEMPERATURE

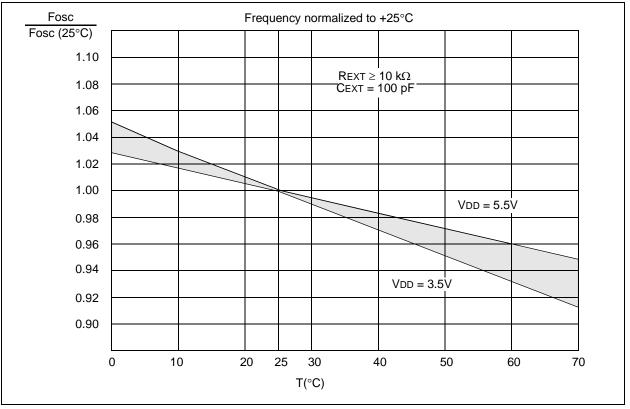


FIGURE 21-11: TYPICAL AND MAXIMUM IPD vs. VDD (SLEEP MODE, ALL PERIPHERALS DISABLED, -40°C to +125°C)

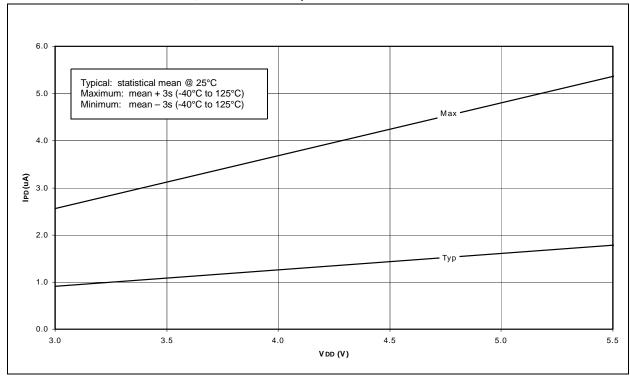
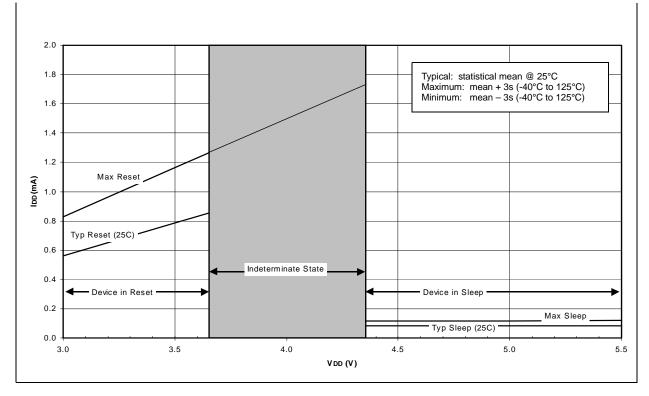
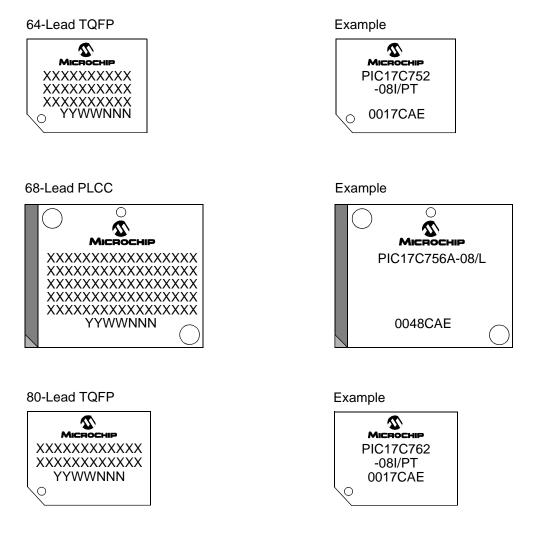


FIGURE 21-12: TYPICAL AND MAXIMUM IPD vs. VDD (SLEEP MODE, BOR ENABLED, -40°C to +125°C)



22.0 PACKAGING INFORMATION

22.1 Package Marking Information



Legend	: XXX Y YY WW NNN @3 *	Customer-specific information Year code (last digit of calendar year) Year code (last 2 digits of calendar year) Week code (week of January 1 is week '01') Alphanumeric traceability code Pb-free JEDEC designator for Matte Tin (Sn) This package is Pb-free. The Pb-free JEDEC designator (e3) can be found on the outer packaging for this package.
Note:	be carrie	nt the full Microchip part number cannot be marked on one line, it will d over to the next line, thus limiting the number of available s for customer-specific information.